Shenzhen Wisdomshow Technology Co.,ltd
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WDS-620 Semi Automatic BGA Rework Station with Infrared + Hot Air Heating for Max PCB Size 470x380mm and ±0.01mm Placement Accuracy

Our Product Introduction

Basic Information

- Place of Origin: CHINA
- Brand Name: WDS
- Certification: CE
- Model Number: WDS620
- Minimum Order Quantity: 1
- Price: US$3080-3280 Unit Price
- Packaging Details: wooden case
- Delivery Time: 3-5days
- Payment Terms: TT
- Supply Ability: 200

Product Specification

- Heating Method: Infrared + Hot Air
- Pcb Size: Max500*450mm Min10*10mm
- Bga Size: Max. 80x80mm
- Pcb Thickness: 0.3-5mm
- Weight: Approx. 55kg
- Dimensions: L800xW780xH810mm
- Power Consumption: 5200W
- Placement Accuracy: ±0.01mm
- Packaging Type: Environmentally Friendly
- Temp Measuring Interface: 1pcs
- Temperaturecontrol: PID Controller
- Applicable Chips: Max 70*70mm Min 1*1 Mm

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Product Description

Product Description:

The Semi Automatic BGA Rework Station is an advanced and reliable piece of equipment designed to meet the high precision demands of modern electronics repair and manufacturing. Engineered for professionals involved in motherboard repair, this rework station combines innovative heating technologies and precise control mechanisms to ensure optimal performance in soldering and desoldering BGA components.

One of the standout features of this BGA Rework Station is its dual heating method, which integrates hot air heating with an Infrared preheating table. This combination guarantees uniform and efficient heating of the BGA components and the PCB, significantly reducing the risk of thermal damage. The hot air heating system directs controlled airflow to the targeted area, ensuring precise temperature application, while the Infrared preheating table warms the entire board evenly. This dual heating approach not only enhances solder joint quality but also increases the success rate of rework processes, making it an indispensable tool for motherboard repair professionals.

In terms of precision, the station boasts an impressive placement accuracy of ±0.01mm. This high level of accuracy is crucial for aligning BGA components correctly on the PCB, ensuring reliable electrical connections and functionality. The semi-automatic operation streamlines the component placement process, reducing manual errors and increasing productivity. Users can confidently handle delicate components, knowing that the system's precision mechanics will deliver consistent results every time.

The Semi Automatic BGA Rework Station is designed to accommodate a wide range of PCB and BGA sizes, making it versatile for various repair and manufacturing tasks. It supports a maximum PCB size of 470x380mm, allowing technicians to work on large motherboards and complex circuit boards with ease. Additionally, the station can handle BGA components up to 80x80mm in size, covering most standard and advanced packaging formats used in the electronics industry.

With dimensions of L800xW780xH810mm, this rework station is compact yet robust, fitting comfortably in most workshop environments without occupying excessive space. Its sturdy construction ensures stability during operation, which is essential for maintaining accuracy and safety when handling sensitive electronic parts.

The user-friendly interface and semi-automatic features make this BGA Rework Station accessible to both experienced technicians and those new to motherboard repair. The intuitive controls allow for easy adjustment of temperature settings, airflow rates, and placement parameters, enabling users to customize the rework process according to the specific requirements of each job. Furthermore, the integration of the Infrared preheating table helps to minimize thermal stress on the motherboard, preserving the integrity of the board and extending its lifespan.

In summary, the Semi Automatic BGA Rework Station is a cutting-edge solution for professionals seeking a reliable and precise tool for BGA soldering and motherboard repair. Its combination of hot air heating and Infrared preheating table ensures superior thermal management, while its high placement accuracy and flexible size compatibility make it suitable for a wide array of electronic components and boards. Compact yet powerful, this rework station is an essential investment for any electronics repair workshop aiming to achieve consistent, high-quality results.

Features:

Product Name: Semi Automatic BGA Rework Station
Weight: Approx. 55kg
Heating Method: Infrared + Hot Air for efficient and even heating
Power Consumption: 5200W
Supports BGA Size: Max. 80x80mm
Supports PCB Size: Max. 470x380mm
Ideal for cpu repair, motherboard repair, and other advanced electronic repairs
Precise temperature control ensures safe and reliable cpu repair
Semi automatic operation enhances efficiency in motherboard repair tasks

Technical Parameters:

PCB Size	Max. 470x380mm
Placement Mode	Semi Automatic
Power Consumption	5200W
Heating Method	Infrared + Hot Air (Three Heating Zones)
Placement Accuracy	±0.01mm
Power Supply	220V/110V
Weight	Approx. 55kg
Dimensions	L800xW780xH810mm
BGA Size	Max. 80x80mm
PCB Thickness	0.3-5mm
Additional Features	Optical Alignment System, Suitable for CPU Repair

Applications:

The WDS620 Semi Automatic BGA Rework Station, manufactured in China by the reputable brand WDS, is an essential tool designed for precise and efficient repair and rework of Ball Grid Array (BGA) components. Certified with CE, this advanced equipment ensures safety and reliability, making it a preferred choice for electronics repair professionals and manufacturing facilities. Its semi automatic placement mode allows users to achieve high accuracy with minimal manual intervention, streamlining the rework process while reducing the risk of damage to sensitive components.

This BGA rework station features a powerful power consumption of 5200W and operates on a versatile power supply of 220V/110V, making it adaptable to various working environments worldwide. The WDS620 is engineered with a three heating zone system, which provides uniform heat distribution essential for the delicate task of soldering and desoldering BGA chips. With a maximum BGA size capacity of 80x80mm, it caters to a wide range of chipsets used in modern electronic devices, including smartphones, laptops, and other consumer electronics.

In practical application, the WDS620 excels in repair workshops, electronics manufacturing lines, and quality control laboratories. It is ideal for occasions where precise temperature control and efficient component replacement are critical, such as PCB rework, prototype development, and component testing. The semi automatic operation simplifies complex procedures, making it suitable for both experienced technicians and those still mastering the art of BGA rework.

The compact design, weighing approximately 55kg, along with its durable packaging in a wooden case, ensures safe transportation and easy installation. With a supply ability of 200 units and a delivery time of 3-5 days, the WDS620 meets urgent production demands and supports small to medium-scale production runs. Payment terms accepted are TT, facilitating smooth transactions.

Overall, the WDS620 Semi Automatic BGA Rework Station is an indispensable device for electronics repair scenarios requiring precision, efficiency, and reliability. Whether used for repairing damaged BGA chips or assembling new components, its advanced features and robust build make it a valuable asset in any electronics maintenance or manufacturing setting.

Customization:

The WDS Semi Automatic BGA Rework Station, model WDS620, is a high-quality product originating from CHINA and certified with CE standards. Designed for precise motherboard repair, this station features an advanced optical alignment system ensuring placement accuracy of ±0.01mm. It supports PCB sizes up to a maximum of 470x380mm with thickness ranging from 0.3 to 5mm.

Utilizing a dual heating method of infrared and hot air heating, the WDS620 guarantees efficient and uniform heat distribution for reliable rework processes. Weighing approximately 55kg, this unit is robust and ideal for both professional and industrial use.

The product is carefully packaged in a wooden case to ensure safe delivery within 3-5 days. With a minimum order quantity of just 1 unit and a supply ability of 200 units, we offer flexible purchasing options. Payment terms are via TT for your convenience.

Choose the WDS620 Semi Automatic BGA Rework Station for precise, efficient, and reliable motherboard repair backed by WDS quality and service.

Support and Services:

The Semi Automatic BGA Rework Station is designed to provide precise and efficient rework capabilities for Ball Grid Array (BGA) components on printed circuit boards (PCBs). It features advanced heating technology, accurate temperature control, and a user-friendly interface to ensure reliable soldering and desoldering processes.

Our technical support team offers comprehensive assistance for the setup, operation, and maintenance of the Semi Automatic BGA Rework Station. We provide detailed user manuals, troubleshooting guides, and software updates to optimize the performance of your equipment.

In addition to technical support, we offer calibration and repair services carried out by certified technicians to maintain the accuracy and longevity of your rework station. Our maintenance packages include routine inspections, component replacements, and firmware upgrades.

For training and consultation, we provide customized sessions to help operators maximize the capabilities of the Semi Automatic BGA Rework Station, ensuring high-quality rework outcomes and minimizing the risk of damage to sensitive components.

We are committed to delivering prompt and effective support to enhance your productivity and ensure the seamless operation of your BGA rework processes.

Packing and Shipping:

Product Packaging:

The Semi Automatic BGA Rework Station is carefully packaged to ensure safe delivery. It is securely placed in a sturdy, custom-designed cardboard box with foam inserts to protect the device from shocks and vibrations during transit. All accessories, including the power cable, soldering tips, user manual, and necessary tools, are neatly organized and packed within the box. The packaging is labeled clearly with product information and handling instructions.

Shipping:

Shipping of the Semi Automatic BGA Rework Station is available worldwide with reliable courier services. The product is shipped promptly after order confirmation and payment clearance. Tracking information is provided to customers to monitor the delivery status. We ensure that all shipments are handled with care, and appropriate insurance options are available to protect against loss or damage during transit. Delivery times may vary based on destination and shipping method selected.

FAQ:

Q1: What is the brand and model number of this Semi Automatic BGA Rework Station?

A1: The brand is WDS and the model number is WDS620.

Q2: Where is the WDS620 Semi Automatic BGA Rework Station manufactured?

A2: It is manufactured in China.

Q3: Does the WDS620 have any certifications?

A3: Yes, the WDS620 Semi Automatic BGA Rework Station is CE certified.

Q4: What is the minimum order quantity for the WDS620?

A4: The minimum order quantity is 1 unit.

Q5: How is the WDS620 Semi Automatic BGA Rework Station packaged for delivery?

A5: The product is packaged in a wooden case to ensure safe delivery.

Q6: What is the typical delivery time for an order of the WDS620?
A6: The delivery time is usually between 3 to 5 days.
Q7: What payment terms are accepted for purchasing the WDS620?
A7: Payment is accepted via TT (Telegraphic Transfer).
Q8: What is the supply ability of the WDS620 Semi Automatic BGA Rework Station?
A8: The supply ability is 200 units.

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